Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at91sam7se512-au

- Provides Reset or Interrupt Signals to the System
- Counter May Be Stopped While the Processor is in Debug State or in Idle Mode

- Real-time Timer (RTT)
  - 32-bit Free-running Counter with Alarm
  - Runs Off the Internal RC Oscillator
- Three Parallel Input/Output Controllers (PIO)
  - Eighty-eight Programmable I/O Lines Multiplexed with up to Two Peripheral I/Os
  - Input Change Interrupt Capability on Each I/O Line
  - Individually Programmable Open-drain, Pull-up Resistor and Synchronous Output
  - Schmitt Trigger on All inputs
- Eleven Peripheral DMA Controller (PDC) Channels
- One USB 2.0 Full Speed (12 Mbits per second) Device Port
  - On-chip Transceiver, Eight Endpoints, 2688-byte Configurable Integrated FIFOs
- One Synchronous Serial Controller (SSC)
  - Independent Clock and Frame Sync Signals for Each Receiver and Transmitter
  - I^2S Analog Interface Support, Time Division Multiplex Support
  - High-speed Continuous Data Stream Capabilities with 32-bit Data Transfer
- Two Universal Synchronous/Asynchronous Receiver Transmitters (USART)
  - Individual Baud Rate Generator, IrDA® Infrared Modulation/Demodulation
  - Support for ISO7816 T0/T1 Smart Card, Hardware Handshaking, RS485 Support
  - Full Modem Line Support on USART1
- One Master/Slave Serial Peripheral Interfaces (SPI)
  - 8- to 16-bit Programmable Data Length, Four External Peripheral Chip Selects
- One Three-channel 16-bit Timer/Counter (TC)
  - Three External Clock Inputs, Two Multi-purpose I/O Pins per Channel
  - Double PWM Generation, Capture/Waveform Mode, Up/Down Capability
- One Four-channel 16-bit PWM Controller (PWMC)
- One Two-wire Interface (TWI)
  - Master, Multi-Master and Slave Mode Support, All Two-wire Atmel EEPROMs Supported
  - General Call Supported in Slave Mode
- One 8-channel 10-bit Analog-to-Digital Converter, Four Channels Multiplexed with Digital I/Os
- SAM-BA®
  - Default Boot program
  - Interface with SAM-BA Graphic User Interface
- IEEE® 1149.1 JTAG Boundary Scan on All Digital Pins
- Four High-current Drive I/O lines, Up to 16 mA Each
- Power Supplies
  - Embedded 1.8V Regulator, Drawing up to 100 mA for the Core and External Components
  - 1.8V or 3,3V VDDIO I/O Lines Power Supply, Independent 3.3V VDDFLASH Flash Power Supply
  - 1.8V VDDCORE Core Power Supply with Brownout Detector
- Fully Static Operation:
  - Up to 55 MHz at 1.8V and 85° C Worst Case Conditions
  - Up to 48 MHz at 1.65V and 85° C Worst Case Conditions
- Available in a 128-lead LQFP Green Package, or a 144-ball LFBGA RoHS-compliant Package

1. Description

Atmel's SAM7SE Series is a member of its Smart ARM Microcontroller family based on the 32-bit ARM7™ RISC processor and high-speed Flash memory.

- SAM7SE512 features a 512-Kbyte high-speed Flash and a 32 Kbyte SRAM.
- SAM7SE256 features a 256-Kbyte high-speed Flash and a 32 Kbyte SRAM.
- SAM7SE32 features a 32-Kbyte high-speed Flash and an 8 Kbyte SRAM.

It also embeds a large set of peripherals, including a USB 2.0 device, an External Bus Interface (EBI), and a complete set of system functions minimizing the number of external components.

The EBI incorporates controllers for synchronous DRAM (SDRAM) and Static memories and features specific circuitry facilitating the interface for NAND Flash, SmartMedia and CompactFlash.

The device is an ideal migration path for 8/16-bit microcontroller users looking for additional performance, extended memory and higher levels of system integration.

The embedded Flash memory can be programmed in-system via the JTAG-ICE interface or via a parallel interface on a production programmer prior to mounting. Built-in lock bits and a security bit protect the firmware from accidental overwrite and preserve its confidentiality.

The SAM7SE Series system controller includes a reset controller capable of managing the power-on sequence of the microcontroller and the complete system. Correct device operation can be monitored by a built-in brownout detector and a watchdog running off an integrated RC oscillator.

By combining the ARM7TDMI processor with on-chip Flash and SRAM, and a wide range of peripheral functions, including USART, SPI, External Bus Interface, Timer Counter, RTT and Analog-to-Digital Converters on a monolithic chip, the SAM7SE512/256/32 is a powerful device that provides a flexible, cost-effective solution to many embedded control applications.

1.1 Configuration Summary of the SAM7SE512, SAM7SE256 and SAM7SE32

The SAM7SE512, SAM7SE256 and SAM7SE32 differ in memory sizes and organization. Table 1-1 below summarizes the configurations for the three devices.

Table 1-1. Configuration Summary

Device	Flash Size	Flash Organization	RAM Size
SAM7SE512	512K bytes	dual plane	32K bytes
SAM7SE256	256K bytes	single plane	32K bytes
SAM7SE32	32K bytes	single plane	8K bytes

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
EBI for NAND Flash Support				
NANDCS	NAND Flash Chip Select Line	Output	Low	
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NANDCLE	NAND Flash Command Line Enable	Output	Low	
NANDALE	NAND Flash Address Line Enable	Output	Low	
SDRAM Controller				
SDCK	SDRAM Clock	Output		Tied low after reset
SDCKE	SDRAM Clock Enable	Output	High	
SDCS	SDRAM Controller Chip Select Line	Output	Low	
BA[1:0]	Bank Select	Output		
SDWE	SDRAM Write Enable	Output	Low	
RAS - CAS	Row and Column Signal	Output	Low	
NBS[3:0]	Byte Mask Signals	Output	Low	
SDA10	SDRAM Address 10 Line	Output		

Note: 1. Refer to Section 6. “/O Lines Considerations” on page 15.

4.2 128-lead LQFP Pinout

Table 4-1. Pinout in 128-lead LQFP Package

1	ADVREF	33	PB31	65	TDI	97	SDCK
2	GND	34	PB30	66	TDO	98	PC8
3	AD7	35	PB29	67	PB2	99	PC7
4	AD6	36	PB28	68	PB1	100	PC6
5	AD5	37	PB27	69	PB0	101	PC5
6	AD4	38	PB26	70	GND	102	PC4
7	VDDOUT	39	PB25	71	VDDIO	103	PC3
8	VDDIN	40	PB24	72	VDDCORE	104	PC2
9	PA20/PGMD8/AD3	41	PB23	73	NRST	105	PC1
10	PA19/PGMD7/AD2	42	PB22	74	TST	106	PC0
11	PA18/PGMD6/AD1	43	PB21	75	ERASE	107	PA31
12	PA17/PGMD5/AD0	44	PB20	76	TCK	108	PA30
13	PA16/PGMD4	45	GND	77	TMS	109	PA29
14	PA15/PGMD3	46	VDDIO	78	JTAGSEL	110	PA28
15	PA14/PGMD2	47	VDDCORE	79	PC23	111	PA27/PGMD15
16	PA13/PGMD1	48	PB19	80	PC22	112	PA26/PGMD14
17	PA12/PGMD0	49	PB18	81	PC21	113	PA25/PGMD13
18	PA11/PGMM3	50	PB17	82	PC20	114	PA24/PGMD12
19	PA10/PGMM2	51	PB16	83	PC19	115	PA23/PGMD11
20	PA9/PGMM1	52	PB15	84	PC18	116	PA22/PGMD10
21	VDDIO	53	PB14	85	PC17	117	PA21/PGMD9
22	GND	54	PB13	86	PC16	118	VDDCORE
23	VDDCORE	55	PB12	87	PC15	119	GND
24	PA8/PGMM0	56	PB11	88	PC14	120	VDDIO
25	PA7/PGMNVALID	57	PB10	89	PC13	121	DM
26	PA6/PGMNOE	58	PB9	90	PC12	122	DP
27	PA5/PGMRDY	59	PB8	91	PC11	123	VDDFLASH
28	PA4/PGMNCMD	60	PB7	92	PC10	124	GND
29	PA3	61	PB6	93	PC9	125	XIN/PGMCK
30	PA2/PGMEN2	62	PB5	94	GND	126	XOUT
31	PA1/PGMEN1	63	PB4	95	VDDIO	127	PLLRC
32	PA0/PGMEN0	64	PB3	96	VDDCORE	128	VDDPLL

6. /O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are Schmitt trigger inputs. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 kΩ.

To eliminate any risk of spuriously entering the JTAG boundary scan mode due to noise on JTAGSEL, it should be tied externally to GND if boundary scan is not used, or put in place an external low value resistor (such as 1 kΩ).

6.2 Test Pin

The TST pin is used for manufacturing test or fast programming mode of the SAM7SE512/256/32 when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of entering the test mode due to noise on the TST pin, it should be tied to GND if the FFPI is not used, or put in place an external low value resistor (such as 1 kΩ).

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied low.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open-drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the NRST pin as system user reset, and the use of the NRST signal to reset all the components of the system.

An external power-on reset can drive this pin during the start-up instead of using the internal power-on reset circuit.

The NRST pin integrates a permanent pull-up of about 100 kΩ resistor to VDDIO.

This pin has Schmitt trigger input.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of erasing the Flash due to noise on the ERASE pin, it should be tied externally to GND, which prevents erasing the Flash from the application, or put in place an external low value resistor (such as 1 kΩ).

This pin is debounced by the RC oscillator to improve the glitch tolerance. When the pin is tied to high during less than 100 ms, ERASE pin is not taken into account. The pin must be tied high during more than 220 ms to perform the re-initialization of the Flash.

  - Individually programmable size between 1K Byte and 1M Byte
  - Individually programmable protection against write and/or user access
  - Peripheral protection against write and/or user access
- Embedded Flash Controller
  - Embedded Flash interface, up to three programmable wait states
  - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
  - Key-protected program, erase and lock/unlock sequencer
  - Single command for erasing, programming and locking operations
  - Interrupt generation in case of forbidden operation

7.4 External Bus Interface

- Integrates Three External Memory Controllers:
  - Static Memory Controller
  - SDRAM Controller
  - ECC Controller
- Additional Logic for NAND Flash and CompactFlash® Support
  - NAND Flash support: 8-bit as well as 16-bit devices are supported
  - CompactFlash support: all modes (Attribute Memory, Common Memory, I/O, True IDE) are supported but the signals _IOIS16 (I/O and True IDE modes) and -ATA SEL (True IDE mode) are not handled.
- Optimized External Bus:
  - 16- or 32-bit Data Bus (32-bit Data Bus for SDRAM only)
  - Up to 23-bit Address Bus, Up to 8-Mbytes Addressable
  - Up to 8 Chip Selects, each reserved to one of the eight Memory Areas
  - Optimized pin multiplexing to reduce latencies on External Memories
- Configurable Chip Select Assignment:
  - Static Memory Controller on NCS0
  - SDRAM Controller or Static Memory Controller on NCS1
  - Static Memory Controller on NCS2, Optional CompactFlash Support
  - Static Memory Controller on NCS3, NCS5 - NCS6, Optional NAND Flash Support
  - Static Memory Controller on NCS4, Optional CompactFlash Support
  - Static Memory Controller on NCS7

7.5 Static Memory Controller

- External memory mapping, 512-Mbyte address space
- 8-, or 16-bit Data Bus
- Up to 8 Chip Select Lines
- Multiple Access Modes supported
  - Byte Write or Byte Select Lines
  - Two different Read Protocols for each Memory Bank

- Multiple device adaptability
  - Compliant with LCD Module
  - Compliant with PSRAM in synchronous operations
  - Programmable Setup Time Read/Write
  - Programmable Hold Time Read/Write
- Multiple Wait State Management
  - Programmable Wait State Generation
  - External Wait Request
  - Programmable Data Float Time

7.6 SDRAM Controller

- Numerous configurations supported
  - **2K, 4K, 8K Row Address Memory Parts**
  - **SDRAM with two or four Internal Banks**
  - **SDRAM with 16- or 32-bit Data Path**
- Programming facilities
  - **Word, half-word, byte access**
  - **Automatic page break when Memory Boundary has been reached**
  - **Multibank Ping-pong Access**
  - **Timing parameters specified by software**
  - **Automatic refresh operation, refresh rate is programmable**
- **Energy-saving capabilities**
  - **Self-refresh, and Low-power Modes supported**
- Error detection
  - **Refresh Error Interrupt**
- **SDRAM Power-up Initialization by software**
- **Latency is set to two clocks (CAS Latency of 1, 3 Not Supported)**
- **Auto Precharge Command not used**
- Mobile SDRAM supported (except for low-power extended mode and deep power-down mode)

7.7 Error Corrected Code Controller

- Tracking the accesses to a NAND Flash device by triggering on the corresponding chip select
- Single bit error correction and 2-bit Random detection.
- Automatic Hamming Code Calculation while writing
  - ECC value available in a register
- Automatic Hamming Code Calculation while reading
  - Error Report, including error flag, correctable error flag and word address being detected erroneous
  - Supports 8- or 16-bit NAND Flash devices with 512-, 1024-, 2048- or 4096-byte pages

7.8 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Eleven channels
  - Two for each USART
  - Two for the Debug Unit
  - Two for the Serial Synchronous Controller
  - Two for the Serial Peripheral Interface
  - One for the Analog-to-digital Converter
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirements
- Peripheral DMA Controller (PDC) priority is as follows (from the highest priority to the lowest):

Receive	DBGU
Receive	USART0
Receive	USART1
Receive	SSC
Receive	ADC
Receive	SPI
Transmit	DBGU
Transmit	USART0
Transmit	USART1
Transmit	SSC
Transmit	SPI

8. Memories

- 512 Kbytes of Flash Memory (SAM7SE512)
  - dual plane
  - two contiguous banks of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 32 lock bits, each protecting 32 lock regions of 64 pages
  - Protection Mode to secure contents of the Flash
- 256 Kbytes of Flash Memory (SAM7SE256)
  - single plane
  - one bank of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 cycles, 10-year data retention capability
  - 16 lock bits, each protecting 16 lock regions of 64 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Flash Memory (SAM7SE32)
  - single plane
  - one bank of 256 pages of 128 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 cycles, 10-year data retention capability
  - 8 lock bits, each protecting 8 lock regions of 32 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM (SAM7SE512/256)
  - Single-cycle access at full speed
- 8 Kbytes of Fast SRAM (SAM7SE32)
  - Single-cycle access at full speed

Figure 8-2. Internal Memory Mapping with GPNVM Bit 2 = 0 (default)

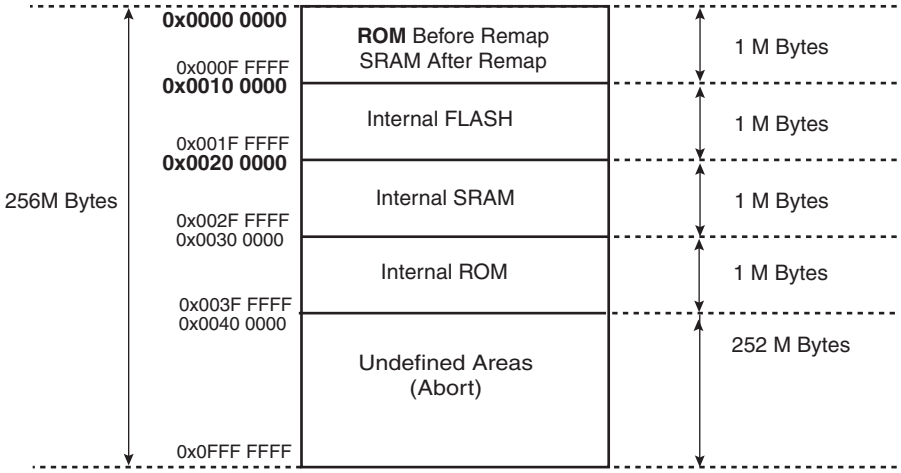
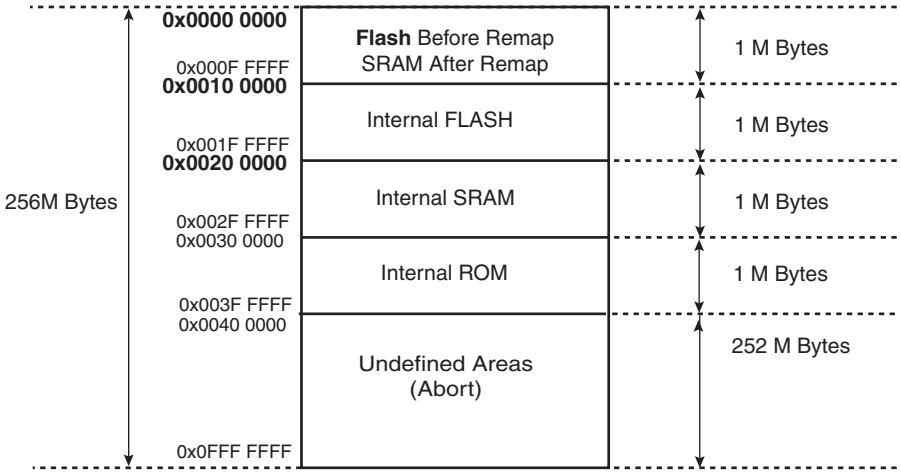


Figure 8-3. Internal Memory Mapping with GPNVM Bit 2 = 1



8.1.2 Embedded Flash

8.1.2.1 Flash Overview

The Flash of the SAM7SE512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. It reads as 131,072 32-bit words.

The Flash of the SAM7SE256 is organized in 1024 pages (single plane) of 256 bytes. It reads as 65,536 32-bit words.

The Flash of the SAM7SE32 is organized in 256 pages (single plane) of 128 bytes. It reads as 8192 32-bit words.

The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.

8.1.4 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the DBGU or the USB Device Port.

- Communication via the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication via the USB Device Port is limited to an 18.432 MHz crystal.

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

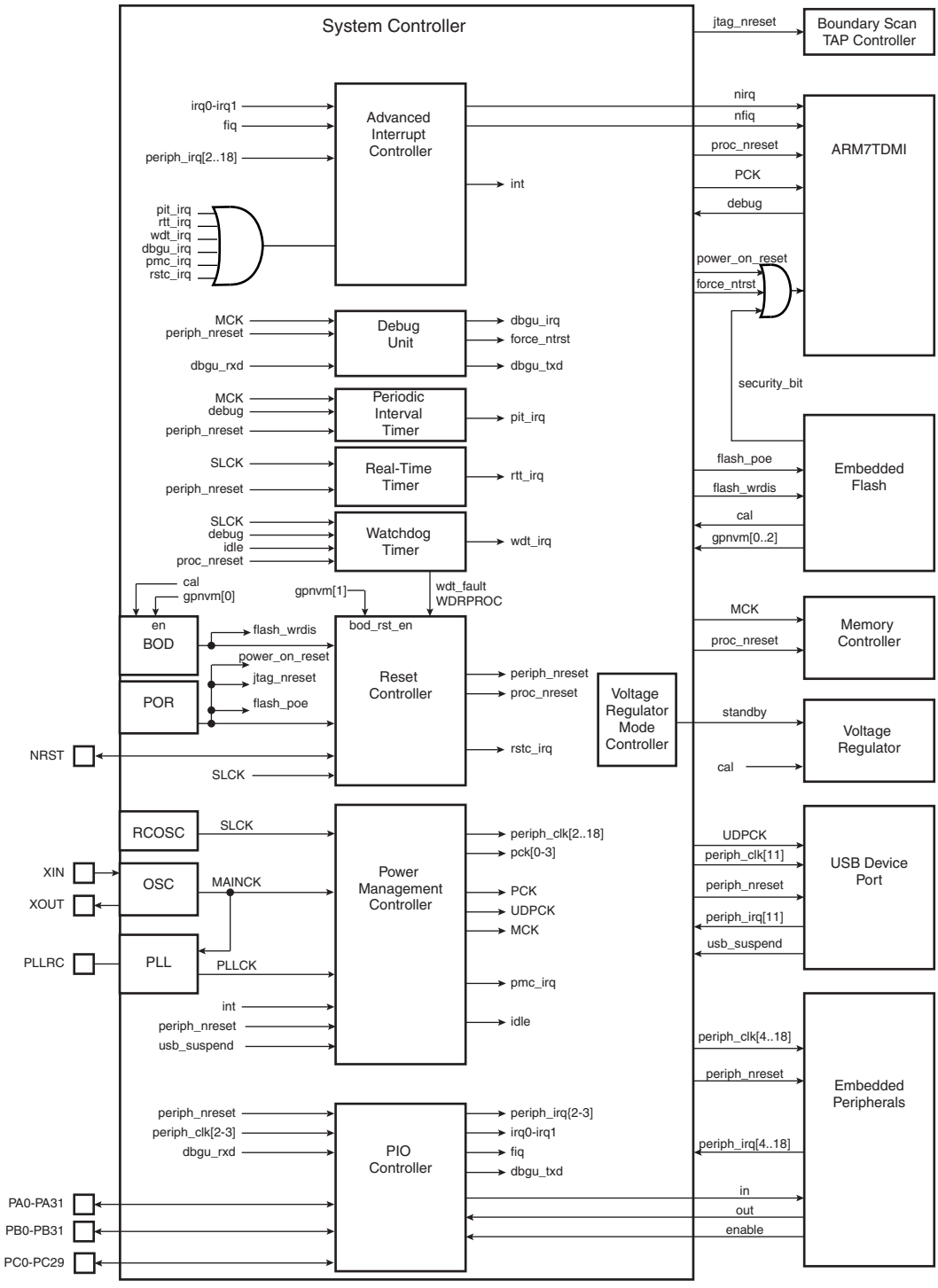
The SAM-BA Boot is in ROM and is mapped in Flash at address 0x0 when GPNVM bit 2 is set to 0.

8.2 External Memories

The external memories are accessed through the External Bus Interface.

Refer to the memory map in Figure 8-1 on page 22.

Figure 9-1. System Controller Block Diagram



9.1 Reset Controller

- Based on one power-on reset cell and a double brownout detector
- Status of the last reset, either Power-up Reset, Software Reset, User Reset, Watchdog Reset, Brownout Reset
- Controls the internal resets and the NRST pin output
- Allows to shape a signal on the NRST line, guaranteeing that the length of the pulse meets any requirement.

9.1.1 Brownout Detector and Power On Reset

The SAM7SE512/256/32 embeds one brownout detection circuit and a power-on reset cell. The power-on reset is supplied with and monitors VDDCORE.

Both signals are provided to the Flash to prevent any code corruption during power-up or power-down sequences or if brownouts occur on the VDDCORE power supply.

The power-on reset cell has a limited-accuracy threshold at around 1.5V. Its output remains low during power-up until VDDCORE goes over this voltage level. This signal goes to the reset controller and allows a full re-initialization of the device.

The brownout detector monitors the VDDCORE and VDDFLASH levels during operation by comparing it to a fixed trigger level. It secures system operations in the most difficult environments and prevents code corruption in case of brownout on the VDDCORE or VDDFLASH.

When the brownout detector is enabled and VDDCORE decreases to a value below the trigger level (Vbot18-, defined as Vbot18 - hyst/2), the brownout output is immediately activated.

When VDDCORE increases above the trigger level (Vbot18+, defined as Vbot18 + hyst/2), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1µs.

The VDDCORE threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 1.68V with an accuracy of ± 2% and is factory calibrated.

When the brownout detector is enabled and VDDFLASH decreases to a value below the trigger level (Vbot33-, defined as Vbot33 - hyst/2), the brownout output is immediately activated.

When VDDFLASH increases above the trigger level (Vbot33+, defined as Vbot33 + hyst/2), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1µs.

The VDDFLASH threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 2.80V with an accuracy of ± 3.5% and is factory calibrated.

The brownout detector is low-power, as it consumes less than 20 µA static current. However, it can be deactivated to save its static current. In this case, it consumes less than 1µA. The deactivation is configured through the GPNVM bit 0 of the Flash.

9.2 Clock Generator

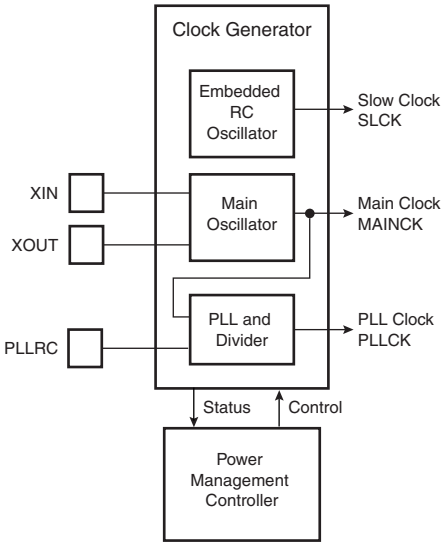
The Clock Generator embeds one low-power RC Oscillator, one Main Oscillator and one PLL with the following characteristics:

- RC Oscillator ranges between 22 KHz and 42 KHz

- Main Oscillator frequency ranges between 3 and 20 MHz
- Main Oscillator can be bypassed
- PLL output ranges between 80 and 220 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-2. Clock Generator Block Diagram



9.3 Power Management Controller

The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCK
- all the peripheral clocks, independently controllable
- three programmable clock outputs

The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.

- Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The purpose of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).

10.6 PIO Controller C Multiplexing

Multiplexing on PIO Controller C

PIO Controller C				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PC0	D0				
PC1	D1				
PC2	D2				
PC3	D3				
PC4	D4				
PC5	D5				
PC6	D6				
PC7	D7				
PC8	D8	RTS1			
PC9	D9	DTR1			
PC10	D10	PCK0			
PC11	D11	PCK1			
PC12	D12	PCK2			
PC13	D13				
PC14	D14	NPCS1			
PC15	D15	NCS3/NANDCS			
PC16	A18	NWAIT			
PC17	A19	NANDOE			
PC18	A20	NANDWE			
PC19	A21/NANDALE				
PC20	A22/REG/NANDCLE	NCS7			
PC21		NWR0/NWE/CFWE			
PC22		NRD/CFOE			
PC23	CFRNW	NCS0			

10.7 Serial Peripheral Interface

- Supports communication with external serial devices
  - Four chip selects with external decoder allow communication with up to 15 peripherals
  - Serial memories, such as DataFlash® and 3-wire EEPROMs
  - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
  - External co-processors
- Master or slave serial peripheral bus interface

- 8- to 16-bit programmable data length per chip select
- Programmable phase and polarity per chip select
- Programmable transfer delays per chip select, between consecutive transfers and between clock and data
- Programmable delay between consecutive transfers
- Selectable mode fault detection
- Maximum frequency at up to Master Clock

10.8 Two Wire Interface

- Master, Multi-Master and Slave Mode Operation
- Compatibility with standard two-wire serial memories
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 Kbit/s
- General Call Supported in Slave Mode

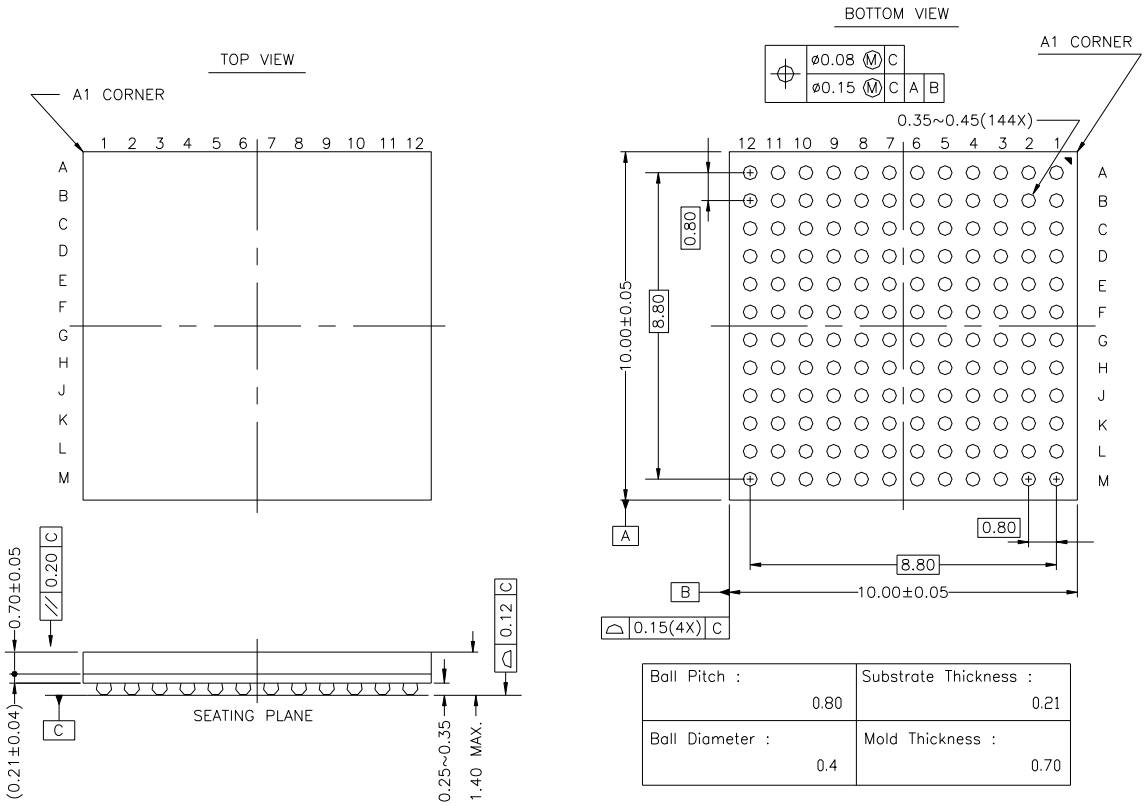
10.9 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
  - 1, 1.5 or 2 stop bits in Asynchronous Mode
  - 1 or 2 stop bits in Synchronous Mode
  - Parity generation and error detection
  - Framing error detection, overrun error detection
  - MSB or LSB first
  - Optional break generation and detection
  - By 8 or by 16 over-sampling receiver frequency
  - Hardware handshaking RTS - CTS
  - Modem Signals Management DTR-DSR-DCD-RI on USART1
  - Receiver time-out and transmitter timeguard
  - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
  - NACK handling, error counter with repetition and iteration limit
- IrDA® modulation and demodulation
  - Communication at up to 115.2 Kbps
- Test Modes
  - Remote Loopback, Local Loopback, Automatic Echo

10.10 Serial Synchronous Controller

- Provides serial synchronous communication links used in audio and telecom applications
- Contains an independent receiver and transmitter and a common clock divider

Figure 11-2. 144-ball LFBGA Package Drawing



All dimensions are in mm

12. Ordering Information

Table 12-1. Ordering Information

Ordering Code	MRL	Package	Package Type	Temperature Operating Range
AT91SAM7SE512B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)

Headquarters

Atmel Corporation
2325 Orchard Parkway
San Jose, CA 95131
USA
Tel: (+1) (408) 441-0311
Fax: (+1) (408) 487-2600

International

Atmel Asia Limited
Unit 01-5 & 16, 19F
BEA Tower, Millennium City 5
418 Kwun Tong Road
Kwun Tong, Kowloon
HONG KONG
Tel: (+852) 2245-6100
Fax: (+852) 2722-1369

Atmel Munich GmbH
Business Campus
Parkring 4
D-85748 Garching b. Munich
GERMANY
Tel: (+49) 89-31970-0
Fax: (+49) 89-3194621

Atmel Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
JAPAN
Tel: (81) 3-3523-3551
Fax: (81) 3-3523-7581

Product Contact

Web Site
www.atmel.com
www.atmel.com/AT91SAM

Technical Support
AT91SAM Support
Atmel techincal support

Sales Contacts
www.atmel.com/contacts/

Literature Requests
www.atmel.com/literature